



- NOTES:
- DNP = "DO NOT POPULATE"
 - REFDEF > 100 added on board
 - built on PMP30165_RevA
 - for short circuit protection following modifications needed:
 use larger packages for D1, D2, D3 (e.g. SMB, SMA, SMA)
 use Transformer with higher saturation current: Isat > 3A

Orderable:	Designed for:	Mod. Date: 6/22/2017
TID #:	Project Title: inverting buckboost flyback	
Number: PMP30165 Rev: B	Sheet Title:	Sheet: 1 of 1
Version control disabled	Assembly Variant [No Variations]	Size: B
Drawn By:	File: PMP30165_RevB_SchDoc	http://www.ti.com
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